SN54ALS112A, SN74ALS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

SDAS199A - APRIL 1982 - REVISED DECEMBER 1994

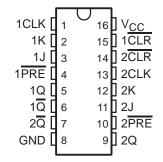
- Fully Buffered to Offer Maximum Isolation From External Disturbance
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY (MHz)	TYPICAL POWER DISSIPATION PER FLIP-FLOP (mW)
'ALS112A	50	6

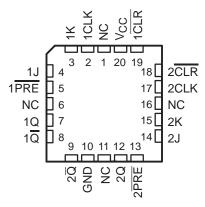
description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the J and K inputs meeting the setup-time requirements is transferred to the outputs on the negative-going edge of the clock pulse (CLK). Clock triggering occurs at a voltage level and is not directly related to the fall time of the clock pulse. Following the hold-time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

SN54ALS112A . . . J PACKAGE SN74ALS112A . . . D OR N PACKAGE (TOP VIEW)



SN54ALS112A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ALS112A is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS112A is characterized for operation from 0° C to 70° C.

FUNCTION TABLE (each flip-flop)

		INPUTS			OUTI	PUTS
PRE	CLR	CLK	J	K	Ø	Q
L	Н	Х	Χ	Х	Н	L
Н	L	X	Χ	X	L	Н
L	L	X	Χ	X	H [†]	H [†]
Н	Н	\downarrow	L	L	Q_0	\overline{Q}_0
Н	Н	\downarrow	Н	L	Н	L
Н	Н	\downarrow	L	Н	L	Н
Н	Н	\downarrow	Н	Н	Tog	gle
Н	Н	Н	Χ	Χ	Q ₀	\overline{Q}_0

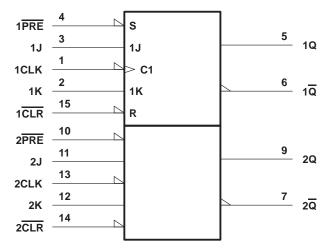
[†] The output levels in this configuration may not meet the minimum levels for V_{OH}. Furthermore, this configuration is nonstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.



SN54ALS112A, SN74ALS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

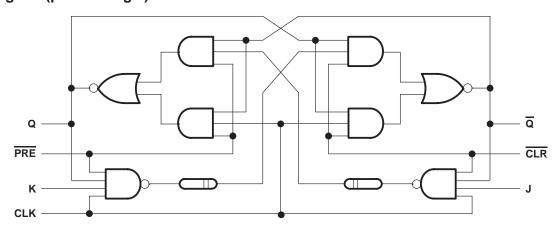
SDAS199A - APRIL 1982 - REVISED DECEMBER 1994

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	
Input voltage, V _I	
	12A –55°C to 125°C
SN74ALS1	12A 0°C to 70°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN54ALS112A, SN74ALS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

SDAS199A - APRIL 1982 - REVISED DECEMBER 1994

recommended operating conditions

			SN	54ALS11	2A	SN7	'4ALS11	2A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			8.0	V
loн	High-level output current				-0.4			-0.4	mA
loL	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		30	MHz
		PRE or CLR low	15			10			
t _W	Pulse duration	CLK high	20			16.5			ns
		CLK low	20			16.5			
	0	Data	25			22			
t _{su}	Setup time before CLK↓	PRE or CLR inactive	22			20			ns
th	Hold time after CLK↓	Data	0			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		METER TEST CONDITIONS				2A	SN7			
		TEST CONDITIONS			TYP [†]	MAX	MIN	TYP†	MAX	UNIT
٧IK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.5			-1.5	V
VOH		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2			V
.,		V 45V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	.,
VOL		V _{CC} = 4.5 V	I _{OL} = 8 mA					0.35	0.5	V
	J, K, or CLK	V00 - 55 V	V 7V		0.1			0.1	4	
Ц	PRE or CLR		V _I = 7 V			0.2			0.2	mA
	J, K, or CLK	V 55V	V 07V			20			20	
lН	PRE or CLR	V _{CC} = 5.5 V,	$V_{I} = 2.7 V$			40			40	μΑ
	J, K, or CLK					-0.2			-0.2	
ΊL	PRE or CLR	V _{CC} = 5.5 V,	$V_{I} = 0.4 V$			-0.4			-0.4	mA
lo [‡]		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
Icc		V _{CC} = 5.5 V,	See Note 1		2.5	4.5		2.5	4.5	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}. NOTE 1: I_{CC} is measured with J, K, CLK, and PRE grounded, then with J, K, CLK, and CLR grounded.

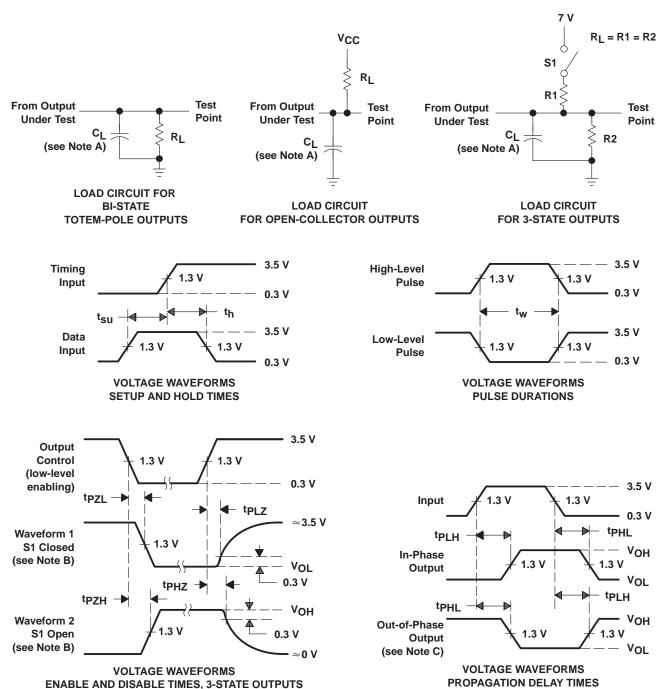
SN54ALS112A, SN74ALS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET SDAS199A - APRIL 1982 - REVISED DECEMBER 1994

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍ C _l R _l T _f	UNIT			
	, ,	, ,	SN54AL	S112A	SN74AL		
			MIN	MAX	MIN	MAX	
f _{max}			25		30		MHz
tpLH	PRE or CLR	0	3	26	3	15	
^t PHL	PRE OF CLR	Q or Q	4	23	4	18	ns
t _{PLH}	CLK	Q or Q	3	23	3	15	nc
^t PHL	OLN	QUIQ	5	24	5	19	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







9-Mar-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
8400002EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8400002EA SNJ54ALS112AJ	Samples
JM38510/37103B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37103B2A	Samples
JM38510/37103BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37103BEA	Samples
M38510/37103B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37103B2A	Samples
M38510/37103BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37103BEA	Samples
SN54ALS112AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS112AJ	Samples
SN74ALS112AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS112A	Samples
SN74ALS112AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS112AN	Samples
SN74ALS112ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS112A	Samples
SNJ54ALS112AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8400002EA SNJ54ALS112AJ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.





9-Mar-2021

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS112A, SN74ALS112A:

Catalog: SN74ALS112A

Military: SN54ALS112A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 17-Dec-2020

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS112ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 17-Dec-2020



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS112ANSR	SO	NS	16	2000	853.0	449.0	35.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (https://www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2021, Texas Instruments Incorporated